

**ABSTRACT**

5 A method for fabricating semiconductor components and  
interconnects includes the steps of providing a substrate,  
such as a semiconductor die, forming external contacts on  
opposing sides of the substrate by laser drilling vias  
through the substrate, and forming conductive members in the  
vias. The conductive members include enlarged terminal  
10 portions that are covered with a non-oxidizing metal. The  
method can be used to fabricate stackable semiconductor  
packages having integrated circuits in electrical  
communication with the external contacts. The method can  
also be used to fabricate interconnects for electrically  
15 engaging packages, dice and wafers for testing or for  
constructing electronic assemblies.

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